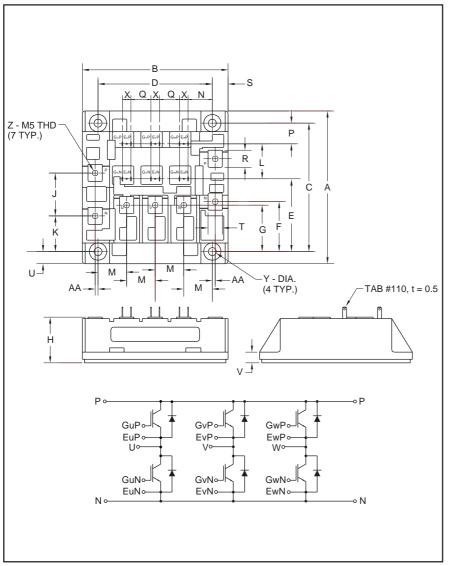
HIGH POWER SWITCHING USE INSULATED TYPE



Outline Drawing and Circuit Diagram

Dimensions	Inches	Millimeters
Α	4.21	107.0
В	4.02	102.0
С	3.543±0.01	90.0±0.25
D	3.15±0.01	80.0±0.25
Е	2.01	51.0
F	1.38	35.0
G	1.28	32.5
Н	1.26 Max.	32.0 Max
J	1.18	30.0
K	0.98	25.0
L	0.96	24.5
М	0.79	20.0
N	0.67	17.0

Inches	Millimeters
0.57	14.5
0.55	14.0
0.47	12.0
0.43	11.0
0.39	10.0
0.33	8.5
0.30	7.5
0.24	6.0
0.22	5.5
M5 Metric	M5
0.08	2.0
	0.57 0.55 0.47 0.43 0.39 0.33 0.30 0.24 0.22 M5 Metric



Description:

Mitsubishi IGBT Modules are designed for use in switching applications. Each module consists of six IGBTs in a three phase bridge configuration, with each transistor having a reverse-connected superfast recovery free-wheel diode. All components and interconnects are isolated from the heat sinking baseplate, offering simplified system assembly and thermal management.

Features:

- □ Low Drive Power
- ☐ Low V_{CE(sat)}
- ☐ Discrete Super-Fast Recovery Free-Wheel Diode
- ☐ High Frequency Operation
- ☐ Isolated Baseplate for Easy Heat Sinking

Applications:

- ☐ AC Motor Control
- ☐ Motion/Servo Control
- UPS
- □ Welding Power Supplies

Ordering Information:

Example: Select the complete part module number you desire from the table below -i.e. CM100TF-24H is a 1200V (V_{CES}), 100 Ampere Six-IGBT Module.

Туре	Current Rating Amperes	V _{CES} Volts (x 50)
СМ	100	24



HIGH POWER SWITCHING USE INSULATED TYPE

Absolute Maximum Ratings, T_i = 25 °C unless otherwise specified

	Symbol	Ratings	Units
Junction Temperature	Тј	-40 to 150	°C
Storage Temperature	T _{stg}	-40 to 125	°C
Collector-Emitter Voltage (G-E SHORT)	V _{CES}	1200	Volts
Gate-Emitter Voltage (C-E SHORT)	V _{GES}	±20	Volts
Collector Current (T _C = 25°C)	Ic	100	Amperes
Peak Collector Current	I _{CM}	200*	Amperes
Emitter Current** (T _C = 25°C)	ΙΕ	100	Amperes
Peak Emitter Current**	I _{EM}	200*	Amperes
Maximum Collector Dissipation ($T_C = 25^{\circ}C, T_j \le 150^{\circ}C$)	P _c	780	Watts
Mounting Torque, M5 Main Terminal	-	1.47 ~ 1.96	N·m
Mounting Torque, M5 Mounting	-	1.47 ~ 1.96	N·m
Weight	-	830	Grams
Isolation Voltage (Main Terminal to Baseplate, AC 1 min.)	V _{iso}	2500	Vrms

^{*}Pulse width and repetition rate should be such that the device junction temperature (T_j) does not exceed T_{j(max)} rating.

**Represents characteristics of the anti-parallel, emitter-to-collector free-wheel diode (FWDi).

Static Electrical Characteristics, T_i = 25 °C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Collector-Cutoff Current	I _{CES}	$V_{CE} = V_{CES}, V_{GE} = 0V$	-	-	1.0	mA
Gate Leakage Current	I _{GES}	$V_{GE} = V_{GES}, V_{CE} = 0V$	-	-	0.5	μΑ
Gate-Emitter Threshold Voltage	V _{GE(th)}	I _C = 10mA, V _{CE} = 10V	4.5	6.0	7.5	Volts
Collector-Emitter Saturation Voltage	V _{CE(sat)}	I _C = 100A, V _{GE} = 15V	-	2.5	3.4**	Volts
		$I_C = 100A, V_{GE} = 15V, T_j = 150^{\circ}C$	_	2.25	_	Volts
Total Gate Charge	Q _G	V _{CC} = 600V, I _C = 100A, V _{GE} = 15V	-	500	-	nC
Emitter-Collector Voltage	V _{EC}	I _E = 100A, V _{GE} = 0V	_	_	3.5	Volts

^{**} Pulse width and repetition rate should be such that device junction temperature rise is negligible.

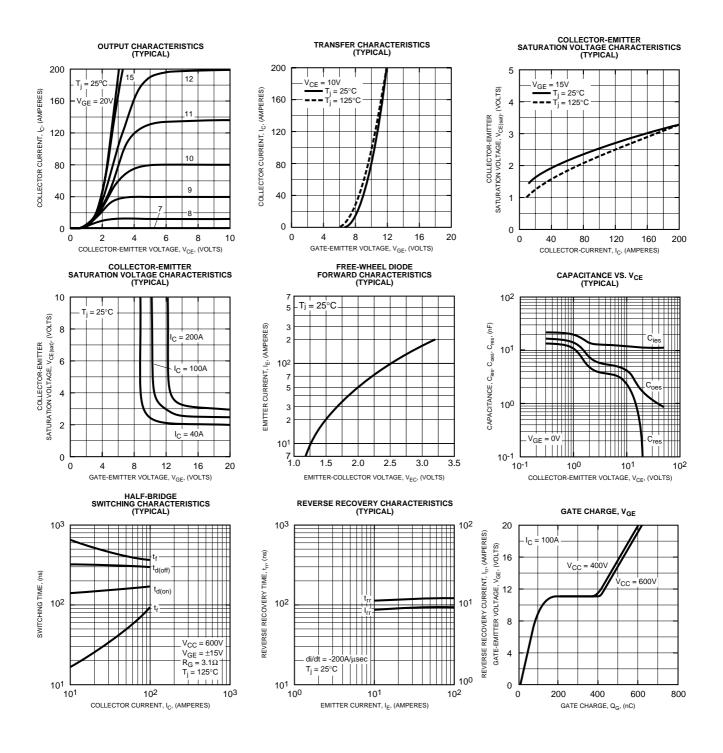
Dynamic Electrical Characteristics, $T_i = 25$ °C unless otherwise specified

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Characteristics		Symbol	Test Conditions	Min.	Тур.	Max.	Units
Input Capacitan	ice	C _{ies}		-	-	20	nF
Output Capacita	ance	C _{oes}	$V_{GE} = 0V$, $V_{CE} = 10V$	_	-	7	nF
Reverse Transfe	er Capacitance	C _{res}		-	-	4	nF
Resistive	Turn-on Delay Time	t _{d(on)}		_	_	250	ns
Load	Rise Time	t _r	VCC = 600V, IC = 100A,	_	-	350	ns
Switching	Turn-off Delay Time	t _{d(off)}	$V_{GE1} = V_{GE2} = 15V, R_G = 3.1\Omega$	_	-	300	ns
Times	Fall Time	t _f	_	-	-	350	ns
Diode Reverse	Recovery Time	t _{rr}	I _E = 100A, di _E /dt = -200A/μs	-	-	250	ns
Diode Reverse	Recovery Charge	Q _{rr}	$I_E = 100A$, $di_E/dt = -200A/\mu s$	_	0.74	_	μC

Thermal and Mechanical Characteristics, T_j = 25 $^{\circ}$ C unless otherwise specified

Characteristics	Symbol	Test Conditions	Min.	Тур.	Max.	Units
Thermal Resistance, Junction to Case	R _{th(j-c)}	Per IGBT	-	_	0.16	°C/W
Thermal Resistance, Junction to Case	R _{th(j-c)}	Per FWDi	-	_	0.35	°C/W
Contact Thermal Resistance	R _{th(c-f)}	Per Module, Thermal Grease Applied	_	-	0.025	°C/W

HIGH POWER SWITCHING USE INSULATED TYPE



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